

1     ABSTRACT OF THE DISCLOSURE

2             The invention encompasses epoxies, epoxy systems, and methods  
3 of forming conductive adhesive connections between electrical nodes.  
4 In one aspect, the invention includes a method comprising: a) providing  
5 a first node; b) providing a second node; c) providing a liquid  
6 conductive epoxy mixture between the first and second nodes, the liquid  
- conductive epoxy mixture comprising a first liquid and a second liquid,  
8 the liquid conductive epoxy mixture having sufficient conductivity that a  
9 15 mil length sample of the liquid conductive epoxy having cross-  
10 sectional dimensions of 50 mil by 2 mil would have a resistance of less  
11 than about 100 ohms along its length between about 10 minutes and  
12 about 20 minutes of combining the first and second liquids; and d)  
13 curing the liquid conductive epoxy to form a conductive adhesive  
14 connection between the first node and the second node. In another  
15 aspect, the invention includes an epoxy comprising: a) a liquid mixture  
16 of a hardener and a base epoxy; and b) a concentration of an ionic  
17 salt within the liquid mixture, the concentration of the ionic salt being  
18 high enough that a 15 mil length sample of the liquid mixture having  
19 cross-sectional dimensions of 50 mil by 2 mil would have a resistance  
20 of less than about 100 ohms along its length in less than or equal to  
21 about 30 minutes of forming the liquid mixture.  
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